

L Number	Hits	Search Text	DB	Time stamp
-	3	((metal adj insulator adj metal) or MIM) and (capacitor adj region) and (conductive adj layer) and (capacitor adj dielectric) and (top adj plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/28 14:00
-	22	((metal adj insulator adj metal) or MIM) and ((interlevel adj dielectric) with conduct\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 15:45
-	2	("20020019123").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 15:16
-	1	((metal adj insulator adj metal) or MIM) and ((cap adj dielectric) with conduct\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 15:45
-	0	((metal adj insulator adj metal) or MIM) and (capacitor adj region) and (conductive adj layer) and (capacitor adj dielectric) and (top adj plate) and (interlayer adj dielectric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 15:47
-	8	((metal adj insulator adj metal) or MIM) and (conductive adj layer) and (capacitor adj dielectric) and (top adj plate) and (interlayer adj dielectric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 15:50
-	179	((metal adj insulator adj metal) or MIM) and (interlayer adj dielectric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/28 10:56
-	47	((metal adj insulator adj metal) or MIM) and (interlayer adj dielectric) and (conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/28 13:47
-	32	Lai and erh-kun	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/28 13:55
-	32	Lai and erh-kun	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/28 13:57
-	2	Lai and erh-kun and mim	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/28 13:58
-	57	((metal adj insulator adj metal) or MIM) and (capacitor adj region)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/28 14:09

-	31	((metal adj insulator adj metal) or MIM) and (capacitor adj region) and interconnect\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/28 14:10
---	----	---	---	------------------